

Briefs: Renesas to make LSIs for 3G mobiles

February 13 2006

Chipmaker Renesas Technology will develop a next-generation large-scale integration circuit, a Japanese daily reported Monday.

The Nihon Keizai Shimbun said that the semiconductor manufacturer will collaborate with NTT DoCoMo, Fujitsu, Mitsubishi Electric and Sharp among others to develop LSIs for third-generation phones.

The plan is to have the product ready for use by the autumn of 2007.

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Citation: Briefs: Renesas to make LSIs for 3G mobiles (2006, February 13) retrieved 23 April 2024 from <https://phys.org/news/2006-02-renesas-lsis-3g-mobiles.html>

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